Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-24 (Canceled)

Claim 25 (Currently amended): A <u>method of making a</u> probe card, ~~made by a~~ <u>said</u> method comprising:

receiving at a computer over a network from a prospective customer information describing a wafer to be tested;

generating from said information a verification package comprising a proposed design of a probe card for testing said wafer; and

communicating over said network with said prospective customer regarding acceptability of said proposed probe card design.

Claim 26 (Currently amended): The ~~probe card~~ <u>method</u> of Claim 25, further comprising providing a graphical interface for use by said prospective customer to enable input of said information describing a wafer to be tested.

Claim 27 (Currently amended): The ~~probe card~~ <u>method</u> of Claim 26, wherein said graphical interface comprises at least one Web page.

Claim 28 (Currently amended): The ~~probe card~~ <u>method</u> of Claim 25, further comprising accepting an order from said prospective customer to manufacture said proposed probe card design.

Claim 29 (Currently amended): The ~~probe card~~ <u>method</u> of Claim 25, further comprising verifying said proposed probe card design.

Claim 30 (Currently amended): The ~~probe card~~ <u>method</u> of Claim 25, wherein said verification package further comprises drawings of said proposed probe card design.

Claim 31 (Currently amended): The ~~probe card~~ method of Claim 25, wherein said communicating step further comprises notifying said prospective customer of proposed modifications to said proposed probe card design.

Claim 32 (Currently amended): The ~~probe card~~ method of Claim 29, wherein said verifying step further comprises simulating operation of said proposed probe card design.

Claim 33 (Currently amended): The ~~probe card~~ method of Claim 29, wherein said verifying step further comprises performing an automated simulation of said proposed probe card design.

Claim 34 (Currently amended): The ~~probe card~~ method of Claim 29, wherein said verifying step further comprises performing a simulation based on particular specifications designated by said prospective customer.

Claim 35 (Currently amended): The ~~probe card~~ method of claim 25 further comprising fabricating a probe card from said proposed probe card design.

Claim 36 (New): A method performed at a server computer of designing a probe card, wherein said probe card provides an interface for test signals between a tester and a semiconductor device to be tested and said probe card comprises tester contacts for making electrical connections with said tester, probes for making electrical connections with terminals of said semiconductor device, and electrical paths connecting ones of said tester contacts with ones of said probes, said method comprising:

     receiving at said server computer from a remotely located customer computer device information describing said semiconductor device;

     receiving at said server computer from said remotely located customer computer probe card information describing said probe card;

     generating at said server computer from said device information and said probe card information a verification package that includes a proposed design for said probe card; and

     communicating to said customer computer said verification package.

Claim 37 (New): The method of claim 36, wherein said step of receiving information describing said probe card comprises:

sending to said customer computer data identifying a plurality of probe card templates stored at said server computer; and

receiving from said customer computer data selecting one of said probe card templates.

Claim 38 (New): The method of claim 36, wherein said device information comprises at least one of an orientation of bond pads on said semiconductor device, dimensions of said semiconductor device, and characteristics of input and/or output signals of said semiconductor device.

Claim 39 (New): The method of claim 38, wherein said probe card information comprises at least one of dimensions of said probe card, orientation of said tester contacts, orientation of said probes, and electrical components of said probe card.

Claim 40 (New): The method of claim 39, wherein said probe card information further comprises information regarding a configuration of said tester.

Claim 41 (New): The method of claim 36, wherein said probe card design comprises a layout of said tester contacts and a layout of said probes.

Claim 42 (New): The method of claim 41, wherein said verification package further comprises information describing said device terminals including locations of said device terminals and a type of signal associated with each said device terminal.

Claim 43 (New): The method of claim 36, wherein said server computer communicates with said customer computer via a computer network.

Claim 44 (New): The method of claim 43, wherein said computer network comprises a public internet.

Claim 45 (New): A method of verifying a design of a probe card, wherein said probe card is designed to provide an interface for test signals between a tester and a semiconductor device to be tested, said method comprising:

accessing design data describing a design of said probe card, wherein said design data comprises data specifying a layout of tester contacts for making electrical connections with said tester, probes for contacting input and/or output terminals of said semiconductor device, and electrical connections between said tester contacts and said probes;

entering information describing operation of said tester; and

initiating a computer simulation of said probe card design.

Claim 46 (New): The method of claim 45, wherein said probe card design data accessed at said accessing step is stored on a server computer, and said steps of accessing, entering, and initiating are performed at a client computer that is remotely located from said server computer.

Claim 47 (New): The method of claim 46, wherein said client computer communicates with said server computer over a computer network.

Claim 48 (New): The method of claim 47, wherein said computer network comprises a public internet.

Claim 49 (New): The method of claim 46 further comprising, in response to said initiating step, simulating said design of said probe card in accordance with said information describing operation of said tester, wherein said step of simulating is performed at said server computer.

Claim 50 (New): The method of claim 49 further comprising receiving at said customer computer results of said simulating step.

Claim 51 (New): The method of claim 49, wherein said initiating step comprises selecting a predetermined simulation sequence stored at said server computer.

Claim 52 (New): The method of claim 49, wherein said step of simulating comprises simulating at least one of powering on said probe card, driving high signals through said probe card, and driving low signals through said probe card.

Claim 53 (New): The method of claim 49, wherein said step of simulating comprises determining at least one of proper functioning of said probe card, acceptability of propagation delays of signals through said probe card, acceptability of signal skew through said probe card, and extent of cross talk between signal paths through said probe card.